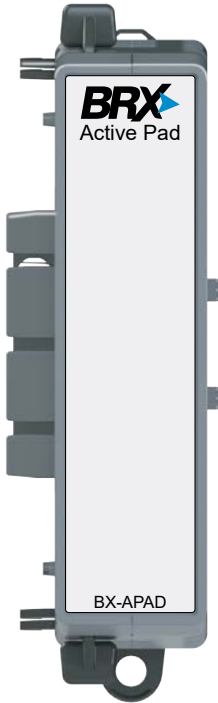


BX-APAD Active Filling



BX-APAD
\$38.00

Active Filling

Active Filling Module Specifications	
Description	BRX active padding module, allows emulation of BRX modules in I/O configuration.
Backplane Power Consumption	0 W
Heat Dissipation	0 W
Weight	85g (3oz)
Software Version	Do-more! Designer v2.7 or later

This module emulates other BRX modules in the I/O configuration of a BRX system. It is configured in software to emulate the address space of a specific BRX module. The padding module can be used to reserve address space so that addressing in subsequent modules does not change if a module is removed. It also allows Intelligent module configurations and data structures to be emulated.



NOTE: Cannot be configured in Remote I/O Bases.

IMPORTANT!



Hot-Swapping Information

Note: This device cannot be Hot Swapped.

BRX Motion Control, Communications and Specialty Expansion Modules



Active Filling Module

One (1) active filling module is available. This module emulates other BRX modules in the I/O configuration of a BRX system. It is configured in software to emulate the address space of a specific BRX module. The filling module can be used to reserve address space so that addressing in subsequent modules does not change if a module is removed.

Active Filling Module	
Part Number	Price
<u>BX-APAD</u>	\$38.00

BRX Motion Control, Communications and Specialty Expansion Modules

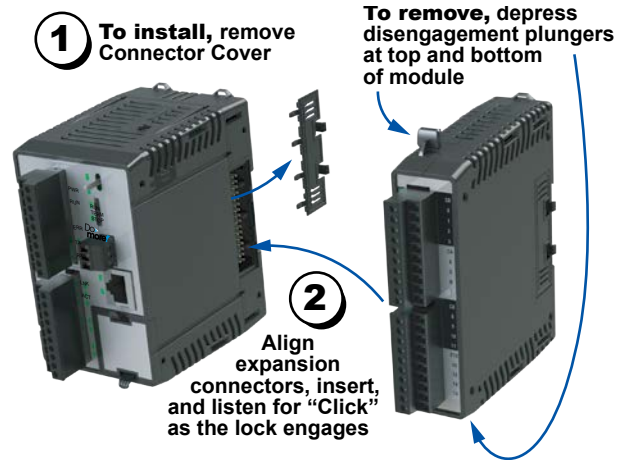
Overview

One of the unique features of the BRX platform is its ability to expand its capability to fit your application solution. One of the ways the BRX platform can do this is by using expansion modules that conveniently "snap on" to the side of any BRX MPU. Once the expansion module has been snapped into place and is added to the project, it instantly adds I/O to the MPU with little to no additional setup required.

The specialty expansion modules give you the ability to add additional high-speed I/O or serial communications as needed. On the front panel of the expansion modules a color scheme and a symbol are used to denote the module type.

High-speed I/O modules have 8-point sinking/sourcing inputs and are available with 8-point sinking or sourcing outputs, all with switching frequencies up to 250kHz. The serial communications modules have 4 serial ports.

The high-speed I/O modules ship without wiring terminals. This allows you to select the termination style that best suits your application. Several wiring options are available, including screw terminal connectors and spring clamp terminal connectors. The serial communications modules ship with a terminal connector installed in each port.



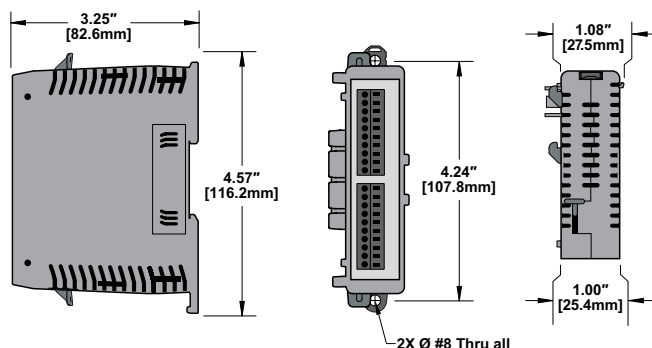
Hot-Swapping Information
 Note: This device cannot be Hot Swapped.

General Specifications

All BRX high-speed input/output modules and serial communications modules have the same general specifications listed in the table below.

General Specifications	
Operating Temperature	0° to 60°C (32° to 140°F)
Storage Temperature	-20° to 85°C (-4° to 185°F)
Humidity	5% to 95% (non-condensing)
Environmental Air	No corrosive gases permitted
Vibration	IEC60068-2-6 (Test Fc)
Shock	IEC60068-2-27 (Test Ea)
Enclosure Type	Open Equipment
Noise Immunity	NEMA ICS3-304
EU Directive	See the "EU Directive" topic in the BRX Help File
Agency Approvals	UL 61010-2 File E185989, Canada and USA, CE Compliant EN61131-2

Dimensions



NOTE: When removing an expansion module make sure there is room for the module to slide away from the system. Failure to do so will result in difficulty removing the module.